SDAS143C - APRIL 1982 - REVISED AUGUST 1995

 Package Options Include Plastic Small-Outline (D) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) 300-mil DIPs

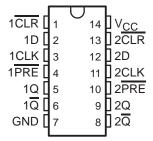
TYPE	TYPICAL MAXIMUM CLOCK FREQUENCY (C <sub>L</sub> = 50 pF) (MHz)	TYPICAL POWER DISSIPATION PER FLIP-FLOP (mW)
'ALS74A	50	6
'AS74A	134	26

#### description

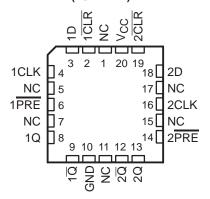
These devices contain two independent positive-edge-triggered D-type flip-flops. A low level at the preset (PRE) or clear (CLR) inputs sets or resets the outputs regardless of the levels of the other inputs. When PRE and CLR are inactive (high), data at the data (D) input meeting the setup-time requirements are transferred to the outputs on the positive-going edge of the clock (CLK) pulse. Clock triggering occurs at a voltage level and is not directly related to the rise time of CLK. Following the hold-time interval, data at the D input can be changed without affecting the levels at the outputs.

The SN54ALS74A and SN54AS74A are characterized for operation over the full military temperature range of -55°C to 125°C. The SN74ALS74A and SN74AS74A are characterized for operation from 0°C to 70°C.

#### SN54ALS74A, SN54AS74A...J PACKAGE SN74ALS74A, SN74AS74A...D OR N PACKAGE (TOP VIEW)



# SN54ALS74A, SN54AS74A . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

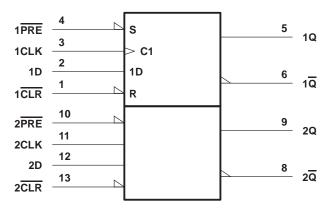
#### **FUNCTION TABLE**

	INP	UTS		OUTI	PUTS
PRE	CLR	CLK	D	Q	Q
L	Н	Х	Χ	Н	L
Н	L	X	Χ	L	Н
L	L	X	Χ	н†	H <sup>†</sup>
Н	Н	$\uparrow$	Н	Н	L
Н	Н	$\uparrow$	L	L	Н
Н	Н	L	Χ	$Q_0$	$\overline{Q}_0$

<sup>†</sup> The output levels in this configuration are not specified to meet the minimum levels for V<sub>OH</sub> if the lows at PRE and CLR are near V<sub>IL</sub> maximum. Furthermore, this configuration is nonstable; that is, it does not persist when PRE or CLR returns to its inactive (high) level.

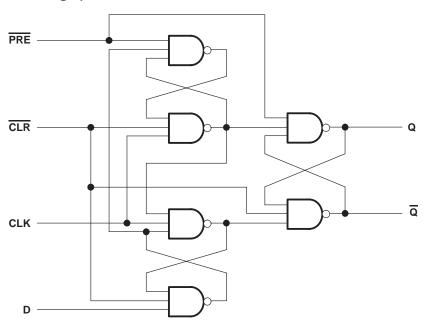
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#### logic symbol†



 $<sup>\</sup>dagger$  This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the D, J, and N packages.

#### logic diagram (positive logic)



### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage, V <sub>CC</sub>	7 V
Input voltage, V <sub>I</sub>	7 V
Operating free-air temperature range, T <sub>A</sub> : SN54ALS74A	-55°C to 125°C
SN74ALS74A	0°C to 70°C
Storage temperature range	-65°C to 150°C

<sup>‡</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.



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#### recommended operating conditions

			SN	54ALS7	4A	SN	74ALS7	4A	
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage		4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage		2			2			V
VIL	Low-level input voltage				0.7			8.0	V
lOH	High-level output current				-0.4			-0.4	mΑ
l <sub>OL</sub>	Low-level output current				4			8	mA
fclock	Clock frequency		0		25	0		34	MHz
		PRE or CLR low	15			15			
t <sub>w</sub>	Pulse duration	CLK high	17.5			14.5			ns
		CLK low	17.5			14.5			
	0	Data	16			15			
tsu	Setup time before CLK↑	PRE or CLR inactive	10			10			ns
th	Hold time after CLK↑	Data	2			0			ns
TA	Operating free-air temperature		-55		125	0		70	°C

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

				SN	54ALS7	4A	SN	74ALS74	4A	
F	PARAMETER	TEST CO	NDITIONS	MIN	TYP <sup>†</sup>	MAX	MIN	TYP†	MAX	UNIT
VIK		V <sub>CC</sub> = 4.5 V,	I <sub>I</sub> = -18 mA			-1.5			-1.5	V
$V_{OH}$		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V},$	$I_{OH} = -2 \text{ mA}$	V <sub>CC</sub> -2			V <sub>CC</sub> -2			V
V	_	V 45 V	$I_{OL} = 4 \text{ mA}$		0.25	0.4		0.25	0.4	.,
VOL		V <sub>CC</sub> = 4.5 V	$I_{OL} = 8 \text{ mA}$					0.35	0.5	V
	CLK or D	V 45.V				0.1			0.1	4
Ц	PRE or CLR	$V_{CC} = 4.5 \text{ V},$	$V_I = 7 V$			0.2			0.2	mA
	CLK or D	V 45.V	V 07V			20			20	٨
ΙΗ	PRE or CLR	$V_{CC} = 4.5 \text{ V},$	$V_{I} = 2.7 \text{ V}$			40			40	μΑ
	CLK or D	V 45.V				-0.2			-0.2	
IIL	PRE or CLR	$V_{CC} = 4.5 \text{ V},$	$V_{I} = 0.4 V$			-0.4			-0.4	mA
1 <sub>0</sub> ‡		$V_{CC} = 5.5 \text{ V},$	V <sub>O</sub> = 2.25 V	-20		-112	-30		-112	mA
ICC		$V_{CC} = 5.5 \text{ V},$	See Note 1		2.4	4		2.4	4	mA

<sup>&</sup>lt;sup>†</sup> All typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .

<sup>†</sup> The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, Ios. NOTE 1: ICC is measured with D, CLK, and PRE grounded, then with D, CLK, and CLR grounded.

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#### switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	C <sub>L</sub> R <sub>L</sub>	= 50 pl = 500 £		V,	UNIT
			SN54A	LS74A	SN74AI	LS74A	
			MIN	MAX	MIN	MAX	
f <sub>max</sub>			25		34		MHz
t <sub>PLH</sub>	PRE or CLR	Q or Q	3	18	3	13	20
<sup>t</sup> PHL	PRE OF CLR	Q or Q	5	17	5	15	ns
t <sub>PLH</sub>	CLK	Q or Q	5	23	5	16	ns
<sup>t</sup> PHL	OLK	Q 01 Q	5	20	5	18	115

<sup>†</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

#### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage, V <sub>CC</sub>	7 V
Input voltage, V <sub>I</sub>	7 V
	S74A –55°C to 125°C
SN74AS	874A 0°C to 70°C
Storage temperature range	–65°C to 150°C

<sup>‡</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

#### recommended operating conditions

			SI	N54AS74	A	SN	174AS74	·A	
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vсс	Supply voltage		4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage		2			2			V
VIL	Low-level input voltage				0.8			8.0	V
lOH	High-level output current				-2			-2	mA
loL	Low-level output current				20			20	mA
fclock*	Clock frequency		0		90	0		105	MHz
		PRE or CLR low	4			4			
t <sub>w</sub> *	Pulse duration	CLK high	4			4			ns
		CLK low	5.5			5.5			
	0 / 11 / 01/4	Data	4.5			4.5			
t <sub>su</sub> *	Setup time before CLK↑	PRE or CLR inactive	2			2			ns
t <sub>h</sub> *	Hold time after CLK↑	Data	0			0			ns
TA	Operating free-air temperature		-55		125	0		70	°C

<sup>\*</sup> On products compliant to MIL-STD-833, Class B, this parameter is based on characterization data but is not production tested.

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# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

				SN	154AS74	Α	SN	74AS74	Α	
1	PARAMETER	TEST COI	TEST CONDITIONS				MIN	TYP†	MAX	UNIT
VIK		V <sub>CC</sub> = 4.5 V,	I <sub>I</sub> = -18 mA			-1.2			-1.2	V
Vон		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V},$	$I_{OH} = -2 \text{ mA}$	V <sub>CC</sub> -2			V <sub>CC</sub> -2			V
VOL		$V_{CC} = 4.5 \text{ V},$	$I_{OL} = 20 \text{ mA}$		0.25	0.5		0.25	0.5	V
l <sub>l</sub>		V <sub>CC</sub> = 5.5 V,	V <sub>I</sub> = 7 V			0.1			0.1	mA
	CLK or D	., 551	V 07V			20			20	•
lн	PRE or CLR	V <sub>CC</sub> = 5.5 V,	V <sub>I</sub> = 2.7 V			40			40	μΑ
	CLK or D	.,	V 0.4V			-0.5			-0.5	4
I L	PRE or CLR	V <sub>CC</sub> = 5.5 V,	$V_{I} = 0.4 V$			-1.8			-1.8	mA
IO <sup>‡</sup>	•	V <sub>CC</sub> = 5.5 V,	V <sub>O</sub> = 2.25 V	-30		-112	-30		-112	mA
Icc		V <sub>CC</sub> = 5.5 V,	See Note 1		10.5	16		10.5	16	mA

<sup>†</sup> All typical values are at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C.

#### switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	C <sub>L</sub> R <sub>L</sub> T <sub>A</sub>	= 50 pF = 500 £ = MIN t	o MAX§		UNIT
			SN54A	S74A	SN74A		
			MIN	MAX	MIN	MAX	
fmax*			90		105		MHz
t <sub>PLH</sub>	PRE or CLR	Q or Q	2	9	2	7.5	20
t <sub>PHL</sub>	PRE OF CLR	Q or Q	2.5	11.5	2.5	10.5	ns
<sup>t</sup> PLH	CLK	Q or Q	2.5	10	3	8	ns
<sup>t</sup> PHL	OLK	300	3.5	10.5	3	9	115

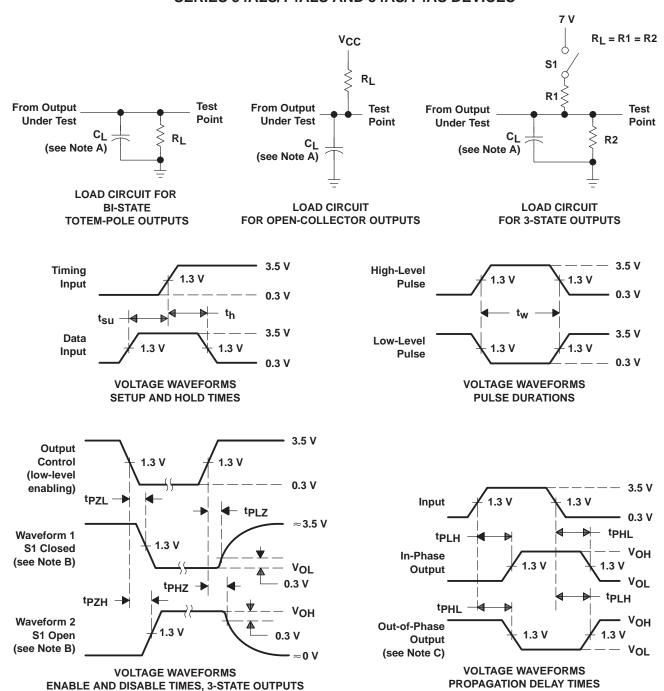
<sup>\*</sup> On products compliant to MIL-STD-833, Class B, this parameter is based on characterization data but is not production tested.

<sup>‡</sup> The output conditions have been chosen to <u>produ</u>ce a current that closely approximates one half of the true short-circuit output current, I<sub>OS</sub>. NOTE 1: I<sub>CC</sub> is measured with D, CLK, and PRE grounded, then with D, CLK, and CLR grounded.

<sup>§</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

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# PARAMETER MEASUREMENT INFORMATION SERIES 54ALS/74ALS AND 54AS/74AS DEVICES



- NOTES: A. C<sub>L</sub> includes probe and jig capacitance.
  - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
  - C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
  - D. All input pulses have the following characteristics: PRR  $\leq$  1 MHz,  $t_f = t_f = 2$  ns, duty cycle = 50%.
  - E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms







24-Aug-2018

#### **PACKAGING INFORMATION**

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
5962-9862701QCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9862701QC A SNJ54AS74AJ	Samples
84011012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	84011012A SNJ54ALS 74AFK	Samples
8401101CA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	8401101CA SNJ54ALS74AJ	Samples
8401101DA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	8401101DA SNJ54ALS74AW	Samples
JM38510/37101B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 37101B2A	Samples
JM38510/37101BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 37101BCA	Samples
M38510/37101B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 37101B2A	Samples
M38510/37101BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 37101BCA	Samples
SN54ALS74AJ	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54ALS74AJ	Samples
SN54AS74AJ	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54AS74AJ	Samples
SN74ALS74AD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS74A	Samples
SN74ALS74ADR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS74A	Samples
SN74ALS74ADRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS74A	Samples
SN74ALS74AN	ACTIVE	PDIP	N	14	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS74AN	Samples
SN74ALS74ANSR	ACTIVE	so	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS74A	Samples
SN74AS74AD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	AS74A	Samples



#### PACKAGE OPTION ADDENDUM

24-Aug-2018

Orderable Device	Status	Package Type	Package Drawing		Package Qty	Eco Plan	Lead/Ball Finish (6)	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN74AS74ADR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	AS74A	Samples
SN74AS74AN	ACTIVE	PDIP	N	14	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74AS74AN	Samples
SN74AS74ANSR	ACTIVE	so	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74AS74A	Samples
SNJ54ALS74AFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	84011012A SNJ54ALS 74AFK	Samples
SNJ54ALS74AJ	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	8401101CA SNJ54ALS74AJ	Samples
SNJ54ALS74AW	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	8401101DA SNJ54ALS74AW	Samples
SNJ54AS74AJ	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9862701QC A SNJ54AS74AJ	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.



#### PACKAGE OPTION ADDENDUM

24-Aug-2018

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

#### OTHER QUALIFIED VERSIONS OF SN54ALS74A, SN54AS74A, SN74ALS74A, SN74AS74A:

Catalog: SN74ALS74A, SN74AS74A

Military: SN54ALS74A, SN54AS74A

NOTE: Qualified Version Definitions:

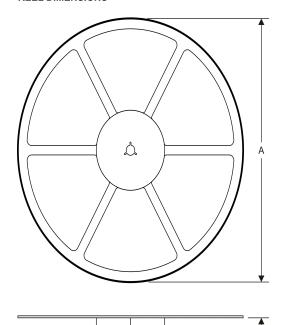
- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

### PACKAGE MATERIALS INFORMATION

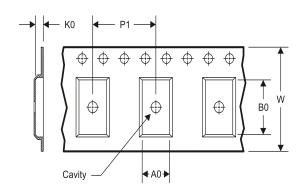
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#### TAPE AND REEL INFORMATION

#### **REEL DIMENSIONS**



#### **TAPE DIMENSIONS**



A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

#### TAPE AND REEL INFORMATION

#### \*All dimensions are nominal

Device		Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALS74ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74ALS74ANSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74AS74ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74AS74ANSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

www.ti.com 14-Jul-2012



\*All dimensions are nominal

7 III dillionorio di o richimal										
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)			
SN74ALS74ADR	SOIC	D	14	2500	367.0	367.0	38.0			
SN74ALS74ANSR	so	NS	14	2000	367.0	367.0	38.0			
SN74AS74ADR	SOIC	D	14	2500	367.0	367.0	38.0			
SN74AS74ANSR	SO	NS	14	2000	367.0	367.0	38.0			

# W (R-GDFP-F14)

#### CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F14



CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary. Refer to the product data sheet for package details.

4040083-5/G





CERAMIC DUAL IN LINE PACKAGE



- 1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This package is hermitically sealed with a ceramic lid using glass frit.
- His package is remitted by sealed with a ceramic its using glass mit.
   Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
   Falls within MIL-STD-1835 and GDIP1-T14.



CERAMIC DUAL IN LINE PACKAGE



# D (R-PDSO-G14)

#### PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.



# D (R-PDSO-G14)

# PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



# N (R-PDIP-T\*\*)

#### PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



# FK (S-CQCC-N\*\*)

#### LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



#### **MECHANICAL DATA**

### NS (R-PDSO-G\*\*)

# 14-PINS SHOWN

#### PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



#### **IMPORTANT NOTICE**

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